TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20200424001.1
Qualification of FFAB as an additional Fab Site option for select BICMOS13 devices
Change Notification / Sample Request

Date: April 28, 2020
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20200424001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DS280DF810ABVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200424001.1	**PCN Date:**	Apr 28, 2020
Title:	Qualification of FFAB as an additional Fab Site option for select BICMOS13 devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jul 28, 2020	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its FFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites			**Additional Sites**		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
MAINEFAB	BICMOS13	200mm	FFAB	BICMOS13	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO :USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected Group:

DS280DF810ABVR	DS280DF810ABVT	DS280DF810ABWR	DS280DF810ABWT

Qualification Report
Approve Date 22-April-2020

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DS280DF810ABWT	QBS Process Device: LMH1297RTVT R	QBS Process Reference LMX2581SQENOPB	QBS Package Reference DS110DF1610SFB
ELFR	Early Life Failure Rate, Ta=115C, Tj~160C	48HRS	-	-	3/2400/0	-
HTOL	Life Test, Ta=115C, Tj~160C	500HRS	-	-	3/231/0	-
HTOL	Life Test, Ta=125C	1000HRS	1/77/0	2/154/0	-	-
AC	Autoclave 121C	96HRS	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96HRS	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -55/125C	700CYC	-	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000HRS	-	-	3/231/0	3/231/0
HBM	ESD - HBM	2000V	1/3/0	-	3/9/0	-
CDM	ESD - CDM	1000V	1/3/0	-	-	-
LU	Latch-up	25C	1/6/0	-	3/18/0	-
LU	Latch-up	85C	1/60	-	3/18/0	-

- QBS: Qual By Similarity
- Qual Device DS280DF810ABWT is qualified at LEVEL3-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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